

Huawei Tecal X6000 V2 Data Center Server



Making IT infrastructure more convenient and green

High Density and Outstanding Deployment Versatility



Huawei X6000 V2 is designed for cloud computing and data center applications. It combines benefits of cabinet servers with high scalability and blade servers with high density and therefore are specially applicable to large-scale deployments and applications.

Huawei X6000 is ranked No. among the SPEC Power servers of the same type due to its superior performance per watt.

Typical application scenarios

Huawei Tecal X6000 V2 is the new-generation blade server that can be applied to fields such as telecommunications, Internet, cloud computing, IDC, virtualization, and high-performance computing centers.

Features

Modular design ensures high scalability

- Four half-width nodes or two full-width nodes can be installed as required.
- High density: A 2U space supports a maximum of four nodes.

Flexible configurations to meet different business requirements

- 2U full width node support up to 4 processors and 48 DIMMs, which is the ideal solution for virtualization applications.
- Every node provides independent I/O expansion slot.
- The hardware acceleration function provided by the Huawei SSD and iNIC helps the X6000 to speed up I/O processing.
- Embedded USB
- Optional TPM

Energy saving and emission reduction make for low carbon IDC

- The power supply, fans, and basic components of the entire system are shared to reduce the

overall power consumption.

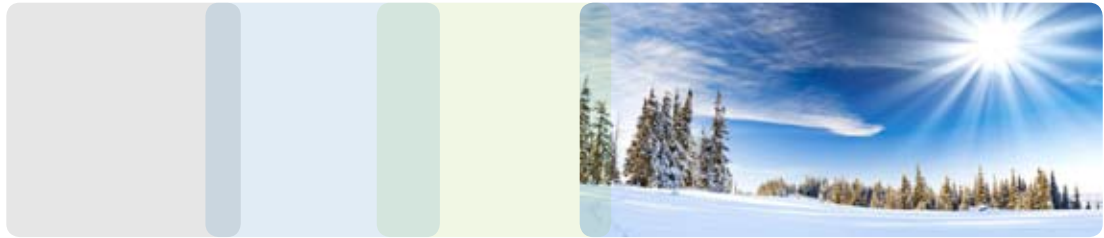
- Intelligent fan control lowers the noise and power consumption.
- Dynamic power capping feature incorporated.

High reliability ensures service continuity.

- Power modules work in 1+1 redundancy mode, and fans work in N+1 redundancy mode.
- Air channels of nodes and power modules are isolated from each other to ensure proper cooling.
- No installed power cable reduces cable failures.
- Embedded "Black Box" function for failure tracking

Simplified maintenance

- Fully compatible and can be configured together with the standard 2U and 1U rack servers.
- Power modules and nodes support hot swapping. No cables need to be inserted or removed. This reduces maintenance workload.
- Remote management achieves the unattended equipment room, ensuring administrators' health.



Product Specifications

X6000 V2 server shelf



Item	Specifications
Dimensions (H x W x D)	87.5 mm x 448 mm x 760 mm (3.44 in. x 17.64 in. x 29.92 in.)
Modular slot	Supports up to four half-width nodes or two full-width nodes.
Power module	Supports a maximum of two 800 W or 1200 W hot-swappable PSUs in 1+1 redundancy mode. Supports load balancing and failover.
Fan module	Provides three fans and supports N+1 redundancy.
I/O subrack	Provides one I/O module that does not support hot swapping and has four PCIe x8 slots.
Power supply	<ul style="list-style-type: none"> • 220 V AC: 200–240 V • 110 V AC: 100–127 V
Backplane	A high-speed passive board, which provides ports for connecting node servers to PEMs and the I/O subrack.
Compliance with the NEBS 1/ETSI standard	Power supply (AC)
Energy-saving standard	Compliance with the 80-PLUS® and Energy Star® standards.
Safety and regulatory	UL, CE, FCC, VCCI

1P half-width node



XH310 Half-Width Node



XH311 Half-Width Node

Item	XH310 Half-Width Node	XH311 Half-Width Node
Dimensions (H x W x D)	41 mm x 540 mm x 210 mm (1.61 in. x 21.26 in. x 8.27 in.)	41 mm x 540 mm x 210 mm (1.61 in. x 21.26 in. x 8.27 in.)
Number of CPU sockets	1	1
CPU model	Supports quad-core Intel® Xeon® E5-1200 series CPUs.	Supports quad-core Intel® Xeon® E5-1200 series CPUs.
Memory slot	Provides 4 DDR3 DIMM slots and a maximum memory capacity of 32 GB	Provides 4 DDR3 DIMM slots and a maximum memory capacity of 32 GB
Number of hard disks	One 3.5-inch SATA hard disk that does not support hot swapping.	Four 2.5-inch SAS hard disks that support hot swapping.
Storage	Provides a maximum storage capacity of 3 TB.	Provides a maximum storage capacity of 4 TB. The following products are optional: RAID 0, RAID 1, RAID 10, and RAID 5 Support RAID 1024 MB Cache and backup battery unit (BBU) for providing power-off protection for 3*24 hours. Batteries or capacitors are optional. Supports 6 Gbps SAS or SATA interfaces.
Hot-swap components	Nodes	Nodes and hard disks
Network	Each node is integrated with two GE controllers that use Intel 82580 chips, and the GE port is located on the rear panel. Each node is integrated with one FE controller (one management network interface), and the FE port is located on the rear panel.	Each node is integrated with two GE controllers that use Intel 82580 chips, and the GE port is located on the rear panel. Each node is integrated with one FE controller (one management network interface), and the FE port is located on the rear panel.
I/O expansion slot	One PCIe 8x slot located on the rear panel	One PCIe 8x slot located on the rear panel
Management	Integrates the BMC to support IPMI 2.0, remote KVM, virtual media, and remote firmware.	Integrates the BMC to support IPMI 2.0, remote KVM, virtual media, and remote firmware.

Item	XH310 Half-Width Node	XH311 Half-Width Node
OS compatibility	Microsoft Windows Sever 2008 32/64bit SUSE Linux Enterprise Server 10.2	Microsoft Windows Sever 2008 32/64bit SUSE Linux Enterprise Server 10.2
Operating environment	10–40°C (50–104°F)	10–40°C (50–104°F)

2P half-width node



XH320 Half-Width Node

Item	XH320 Half-Width Node
Dimensions (H x W x D)	41 mm x 540 mm x 210 mm (1.61 in. x 21.26 in. x 8.27 in.)
Number of CPU sockets	2
CPU model	Supports eight-core Intel® Xeon® E5-2400 series CPUs
Memory slot	Provides 12 DDR3 DIMM slots and a maximum memory capacity of 384 GB
Number of hard disks	Four 2.5-inch SAS hard disks that support hot swapping.
Storage	Provides a maximum storage capacity of 4 TB. The following products are optional: RAID 0, RAID 1, RAID 10, and RAID 5 Support RAID 1024 MB Cache and backup battery unit (BBU) for providing power-off protection for 3*24 hours. Batteries or capacitors are optional. Supports 6 Gbps SAS or SATA interfaces.
Hot-swap components	Nodes and hard disks
Network	Each node is integrated with two GE controllers that use Intel 82580 chips, and the GE port is located on the rear panel. Each node is integrated with one FE controller (one management network interface), and the FE port is located on the rear panel.
I/O expansion slot	One PCIe 8x slot located on the rear panel
Management	Integrates the BMC to support IPMI 2.0, remote KVM, virtual media, and remote firmware.
OS compatibility	Microsoft Windows Sever 2008 32/64bit; Red Hat Enterprise Linux 5. 6. SUSE Linux Enterprise Server 10.2 and 11.2
Operating environment	10–35°C (50–95°F)

2P full-width node



XH620



XH621

Item	XH620	XH621
Dimensions (H x W x D)	41 mm x 540 mm x 423 mm (1.61 in. x 21.26 in. x 16.65 in.)	41 mm x 540 mm x 423 mm (1.61 in. x 21.26 in. x 16.65 in.)
Number of CPU sockets	2	2
CPU model	Supports eight-core Intel® Xeon® E5-2600 series CPUs.	Supports eight-core Intel® Xeon® E5-2600 series CPUs.
Memory slot	Provides 24 DDR3 DIMM slots and a maximum memory capacity of 768 GB	Provides 24 DDR3 DIMM slots and a maximum memory capacity of 768 GB
Number of hard disks	Four 2.5-inch SAS hard disks that support hot swapping.	Eight 2.5-inch SAS hard disks that support hot swapping.
Storage	Provides a maximum storage capacity of 4 TB. The following products are optional: RAID 0, RAID 1, RAID 10, and RAID 5 Support RAID 1024 MB Cache and backup battery unit (BBU) for providing power-off protection for 3*24 hours. Batteries or capacitors are optional. Supports 6 Gbps SAS or SATA interfaces.	Provides a maximum storage capacity of 8 TB. The following products are optional: RAID 0, RAID 1, RAID 10, and RAID 5 Support RAID 1024 MB Cache and backup battery unit (BBU) for providing power-off protection for 3*24 hours. Batteries or capacitors are optional. Supports 6 Gbps SAS or SATA interfaces.
Hot-swap components	Nodes and hard disks	Nodes and hard disks
Network	Each node is integrated with two GE controllers that use Intel 82580 chips, and the GE port is located on the rear panel. Each node is integrated with one FE controller (one management network interface), and the FE port is located on the rear panel.	Each node is integrated with two GE controllers that use Intel 82580 chips, and the GE port is located on the rear panel. Each node is integrated with one FE controller (one management network interface), and the FE port is located on the rear panel.

2P full-width nodes



XH620



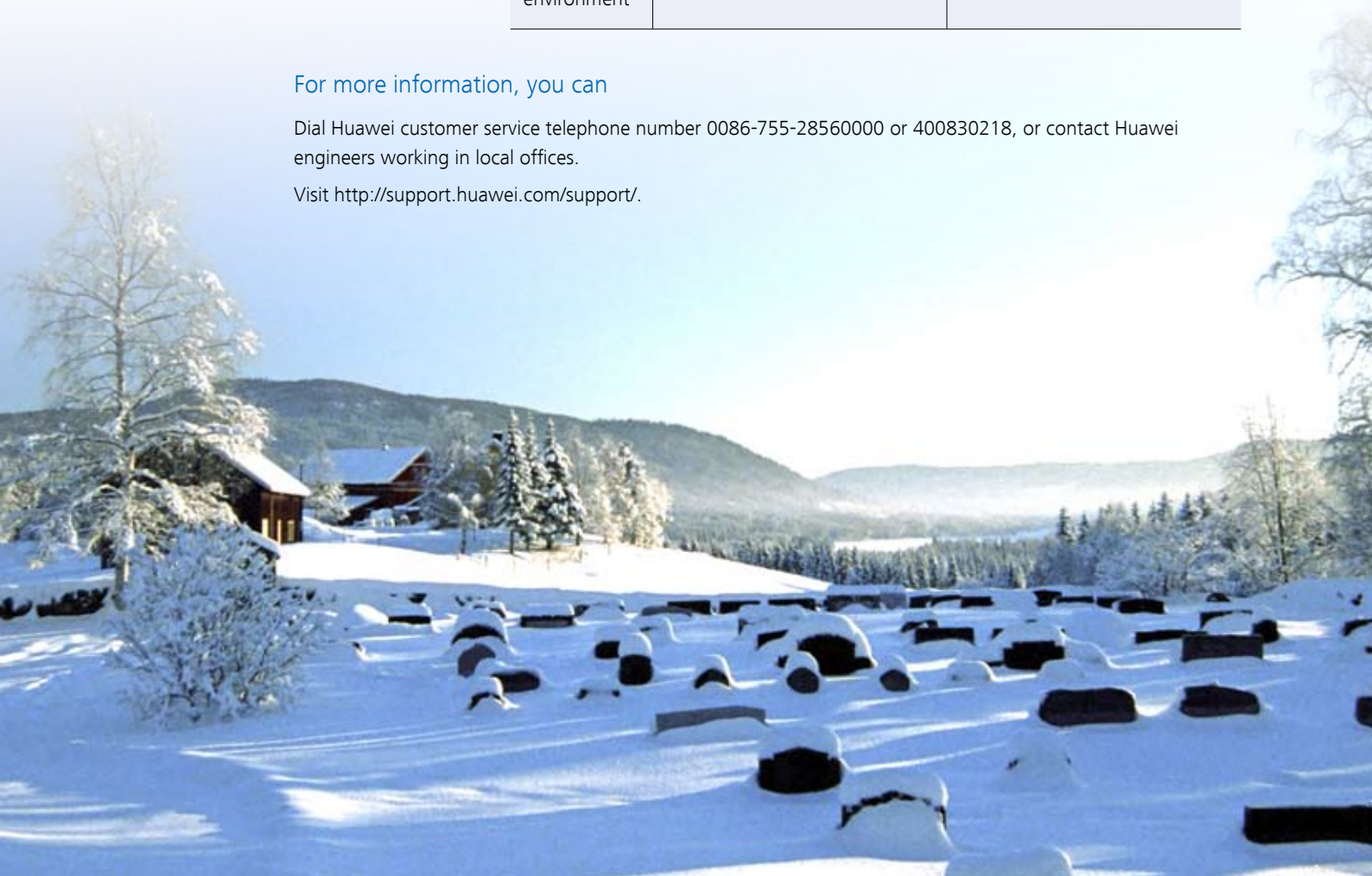
XH621

Item	XH620	XH621
I/O expansion slot	Two PCIe 16x slots (3/4 full height) located on the front panel Two PCIe 8x slots located on the rear panel	One PCIe 8x slot located on the front panel Two PCIe 8x slots located on the rear panel
Management	Integrates the BMC to support IPMI 2.0, remote KVM, virtual media, and remote firmware.	Integrates the BMC to support IPMI 2.0, remote KVM, virtual media, and remote firmware.
OS compatibility	Microsoft Windows Sever 2008 Red Hat Enterprise Linux 5,6 SUSE Linux Enterprise Server 10.4 and 11.1 Citrix XenServer 5.6.0; Vmware ESX 4.1.0 ; GreatTurbo Enterprise Linux 11.3	Microsoft Windows Sever 2008 Red Hat Enterprise Linux 5,6 SUSE Linux Enterprise Server 10.4 and 11.1 Citrix XenServer 5.6.0; Vmware ESX 4.1.0 ; GreatTurbo Enterprise Linux 11.3
Operating environment	10–35°C (50–95°F)	10–35°C (50–95°F)

For more information, you can

Dial Huawei customer service telephone number 0086-755-28560000 or 400830218, or contact Huawei engineers working in local offices.

Visit <http://support.huawei.com/support/>.







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HUAWEI TECHNOLOGIES CO.,LTD.
Huawei Industrial Base
Bantian Longgang
Shenzhen 518129,P.R.China
Tel: +86 755 28780808

www.huawei.com